

sub. C1
substrate, and having a cavity formed to store said electronic element therein; and
a cover member to hermetically seal over the cavity of said frame member, in
which said electronic element is stored, wherein electrodes are formed at or in
vicinity of positions of the terminals of said electronic element stored within said
cavity, to electrically conduct said interior terminal portions for connection to outside
said electronic device, wherein said cover member, said frame member and said
substrate form a hermetically sealed space in which said electronic element is stored
without being in direct physical contact with any of the cover member, the frame
member or the substrate.

22. An electronic device as defined in the claim 21, wherein said electrodes to
electrically conduct said interior terminal portions to the outside are plated through-
holes formed in said substrate, being filled with non-conductive resin therein.

23. An electronic device as defined in the claim 21, wherein said electrodes to
electrically conduct said interior terminal portions to the outside are flat through-holes
formed in said substrate.

24. An electronic device as defined in the claim 21, wherein exterior terminals for
connection, being electrically connected with said internal terminal portion, are
provided on a lower surface of said substrate.

25. An electronic device as defined in the claim 21, wherein conductors formed on
said substrate, exposing to said cavity and the outside are made from layers of noble
metal.